



Material Content Data Sheet



Sales Product Name		BSC750N10ND G		Issued		29. August 2013		
MA#		MA000866714						
Package		PG-TDSON-8-4		Weight*		97.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.354	2.42	2.42	24190	24190
leadframe	non noble metal	iron	7439-89-6	0.045	0.05		460	
	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	copper	7440-50-8	44.654	45.91	45.97	458973	459571
wire	non noble metal	aluminium	7429-90-5	0.264	0.27	0.27	2716	2716
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		926	
	plastics	epoxy resin	-	6.396	6.57		65735	
	inorganic material	silicondioxide	60676-86-0	38.553	39.63	46.29	396265	462926
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13440	13440
plating	non noble metal	nickel	7440-02-0	0.048	0.05		493	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.05	1	494
solder	noble metal	silver	7440-22-4	0.089	0.09		917	
	non noble metal	tin	7440-31-5	0.071	0.07		733	
	non noble metal	lead	7439-92-1	3.406	3.50	3.66	35013	36663
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com